

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	1	'wafer notch' and 'curvature' and 'symmetric'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:13
L4	245	@ad<="20040112" and ('arc' or 'curcular') with 'notch' and 'symmetrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:59
L5	30	@ad<="20040112" and ('arc' or 'curcular') with 'notch' same 'symmetrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:59
L6	0	@ad<="20040112" and 'wafer' and ('arc' or 'curcular') with 'notch' same 'symmetrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:08
L7	118	@ad<="20040112" and 'wafer' and ('arc' or 'curcular') with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:59
L8	57	@ad<="20040112" and 'wafer' same ('arc' or 'curcular') with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:59
L9	19	@ad<="20040112" and 'wafer' and ('arc' or 'curcular') with 'notch' and 'symmetrical'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:38
L10	31	YAMAZAKI-KEISUKE.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:24
L11	49	@ad<="20040112" and 'wafer' and 'notch' with 'smooth'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:40
L12	2	"20040113236"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 13:39

L13	4	@ad<="20040112" and 'wafer' and 'notch' with 'smooth edge'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:05
L14	0	@ad<="20040112" and 'semiconductor' and 'notch' with 'same shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:05
L15	0	@ad<="20040112" and 'semiconductor' and 'notch' with 'smooth shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:05
L16	90	@ad<="20040112" and 'semiconductor' and 'notch' with 'shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:07
L17	5	@ad<="20040112" and 'semiconductor' and 'notch' with 'same curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:08
L18	0	@ad<="20040112" and 'wafer' and 'notch' with 'same curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:08
L19	41	@ad<="20040112" and 'wafer' and 'notch' with 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:29
L20	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/20 14:14
L21	1	"5458529".PN.	USPAT; USOCR	OR	ON	2005/05/20 14:14
L22	0	yoshiharu-hidaka.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:29
L23	67	Hidaka-Yoshiharu.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 14:36
L24	6	Ikenouchi-Katsuyuki.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:00

L25	701	('trench' or 'via') same 'nitride' same 'oxynitride' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:01
L26	240	('trench' or 'via') same 'nitride' same 'oxynitride' same 'thickness' with 'angstrom'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:03
L27	10	('trench' or 'via') same 'liner' with 'nitride' with 'oxynitride' same 'thickness' with 'angstrom'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:15
L28	1	"6509266".PN.	USPAT; USOCR	OR	ON	2005/05/20 15:11
L29	1	"6489233".PN.	USPAT; USOCR	OR	ON	2005/05/20 15:12
L30	20	('trench' or 'via') same 'liner' with 'nitride' with 'oxynitride' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:28
L32	641	'capacitor' and 'dielectric' same 'nitride' with 'oxynitride' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:29
L33	99	'trench capacitor' and 'nitride' with 'oxynitride' same 'thickness'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 15:29
S1	577	@ad<="20020111" and (438/455).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:44
S2	158	@ad<="20020111" and (438/456).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:40
S3	53	@ad<="20020111" and (438/457).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:57
S4	375	@ad<="20020111" and (438/458).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:58

S5	548	@ad<="20020111" and (438/459).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:58
S6	453	@ad<="20020111" and (438/460).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:58
S7	363	@ad<="20020111" and (427/289).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S8	292	@ad<="20020111" and (451/53).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:03
S9	2016	@ad<="20020111" and (438/690-692).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:19
S10	249	@ad<="20020111" and (451/44).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S11	363	@ad<="20020111" and (427/289).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:05
S12	312	@ad<="20020111" and (257/e21.237).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S13	292	@ad<="20020111" and (257/e21.23).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:13
S14	393	@ad<="20020111" and (257/618).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S15	454	@ad<="20020111" and (257/620).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 09:24

S16	151	@ad<="20020111" and (438/413).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 08:19
S17	154	@ad<="20020111" and (257/e21.238).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S18	252	@ad<="20020111" and (257/e21.239).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S19	303	@ad<="20020111" and (257/e21.002).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S20	183	@ad<="20020111" and (257/e21.022).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:42
S21	1	'9-251934'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:24
S22	116	'shin-etsu' and 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:25
S23	1	'JP 9-251934'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:04
S24	1	'JP09251934'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:20
S25	2	'09251934'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:21
S26	3	'06061201'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:23

S27	3	"02275613"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:23
S28	76	'shin-etsu handotai' and 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 13:46
S29	336	'hitachi ltd' and 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:26
S30	33	'hitachi ltd' and 'wafer' same 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 14:08
S31	70	'shin-etsu' and 'wafer' same 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:50
S32	191	@ad<="20020111" and 'wafer' and 'chamfered' same 'polished'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:52
S33	2	@ad<="20020111" and 'wafer' and 'chamfered' same 'polished' and 'non-mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:54
S34	2	@ad<="20020111" and 'wafer' and 'chamfered' and 'polished' and 'non-mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:54
S35	8	@ad<="20020111" and 'wafer' and 'chamfered' and 'polished' and 'unpolished'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:57
S36	23	@ad<="20020111" and 'wafer' and 'chamfered' same 'mirror finished'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:58
S37	23	@ad<="20020111" and 'wafer' and 'chamfered' same 'mirror' adj1 'finished'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 13:58

S38	0	@ad<="20020111" and 'wafer' and 'chamfered' same 'mirror' adj1 'finished' same 'non mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/24 07:56
S39	2	@ad<="20020111" and 'wafer' and 'chamfered' same 'non mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:03
S40	3	@ad<="20020111" and 'wafer' and 'chamfered' and 'non mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:03
S41	2	@ad<="20020111" and 'wafer' and 'chamfered' and 'non-mirror'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:03
S42	368	ota-yutaka.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:25
S43	50	ota-yutaka.in. and 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/08/23 14:25
S44	77	'shin-etsu handotai' and 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 13:47
S45	33	'hitachi ltd' and 'wafer' same 'chamfered'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 14:19
S46	55	'wafer' same 'chamfered' same 'polish'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 14:20
S47	65	'chamfered' with 'polish'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 14:20
S48	1	"20030110803".PN.	US-PGPUB	OR	ON	2005/01/05 14:22
S49	1	"20030109202".PN.	US-PGPUB	OR	ON	2005/01/05 14:22
S50	1	"20020121110".PN.	US-PGPUB	OR	ON	2005/01/05 14:22

S51	586	@ad<="20020111" and (438/455).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:40
S52	162	@ad<="20020111" and (438/456).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:40
S53	1271	@ad<="20020111" and (438/457-460).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S54	367	@ad<="20020111" and (427/289).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S55	323	@ad<="20020111" and (257/e21.237).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S56	395	@ad<="20020111" and (257/618).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S57	251	@ad<="20020111" and (451/44).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S58	170	@ad<="20020111" and (257/e21.238).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S59	252	@ad<="20020111" and (257/e21.239).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S60	303	@ad<="20020111" and (257/e21.002).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:41
S61	189	@ad<="20020111" and (257/e21.022).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/10 10:42

S62	353	@ad<="20020111" and (438/690).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:33
S63	2	"20040140536"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/08 08:39
S64	560	'wafer notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/08 11:09
S65	560	'wafer notch' or 'wafer chafer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/19 16:01
S66	636	'wafer notch' or 'wafer chamfer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/04/08 11:11
S67	34	'wafer notch' and 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 12:12
S68	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:04
S69	1	"5458529".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:05
S70	1	"5445554".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:06
S71	1	"5445554".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:06
S72	1	"4905425".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:06
S73	1	"5185965".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:06
S74	1	"5117590".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:07
S75	1	"4783225".PN.	USPAT; USOCR	OR	ON	2005/05/19 16:08
S76	19	'wafer notch' same 'radius'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:36
S77	1	"6341996".PN.	USPAT; USOCR	OR	ON	2005/05/20 08:21

S78	1	"5083378".PN.	USPAT; USOCR	OR	ON	2005/05/20 08:21
S79	2	"2991555".PN.	USPAT; USOCR	OR	ON	2005/05/20 08:21
S80	220	'wafer' and 'notch' and 'radius' and 'shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:37
S81	3	'wafer' and 'notch' and 'radius' and 'shoulder' same 'arc'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:40
S82	5	'wafer' and 'shoulder' with 'circular' with 'arc'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:43
S83	3	@ad<="20040112" and 'wafer' and 'notch' same 'shoulder circular'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:45
S84	183	@ad<="20040112" and 'wafer' and 'notch' same 'shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:49
S85	4	@ad<="20040112" and 'wafer' and 'notch' same 'shoulder' same 'radius'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:46
S86	28	@ad<="20040112" and 'wafer' with 'notch' same 'shoulder'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:04
S87	17	@ad<="20040112" and 'wafer' with 'eccentric' with 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 08:55
S88	1	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' with 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:05
S89	14	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' and 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:05

S90	2	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' same 'curvature'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:05
S91	4	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' same 'radii'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:05
S92	4	@ad<="20040112" and 'wafer' with 'notch' and 'shoulder' same 'radius'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:09
S93	38	@ad<="20040112" and 'semiconductor' and 'notch' and 'shoulder' same ('curvature' or 'radius' or 'radii')	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:10
S94	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:31
S95	1	"4167836".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:31
S96	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:32
S97	1	"5289661".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:32
S98	1720	@ad<="20020111" and (451/44).ccls. or (451/258).ccls. or (451/57).ccls. or (451/65).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/20 09:34
S99	1	"5490811".PN.	USPAT; USOCR	OR	ON	2005/05/20 09:34